

CLAIMS

1. A sheet for sealing, which is a thermosetting
sheet ~~forused to~~ sealing an electronic device, comprising a
5 thermoplastic resin, wherein
one surface of the sheet having a surface roughness
(Ra) of 3 μm or less.

2. The sheet for sealing according to claim 1,
10 wherein a colorant is added to the side of the one surface
of the sheet.

~~3. A method for manufacturing a semiconductor device,~~
~~comprising:~~
15 ~~a step A of flip chip bonding an electronic device~~
~~onto a circuit-forming surface of a semiconductor wafer,~~
~~and~~
~~a step B of embedding the electronic device flip chip~~
~~bonded onto the semiconductor wafer into a sheet for~~
20 ~~sealing to form a sealed body,~~
~~wherein a surface of the sheet for sealing, the~~
~~surface being opposite to a surface of the sheet that faces~~
~~the semiconductor wafer, has a surface roughness (Ra) of 3~~
 ~~μm or less.~~

25 ~~4. The method for manufacturing a semiconductor~~
~~device according to claim 3, wherein a colorant is added to~~
~~the side of the sheet surface opposite to the surface of~~
~~the sheet that faces the semiconductor wafer.~~